







Certificate TH97/10561QM

Certificate TW00/17276EM

M1 - M7

PRV: 50 - 1000 Volts

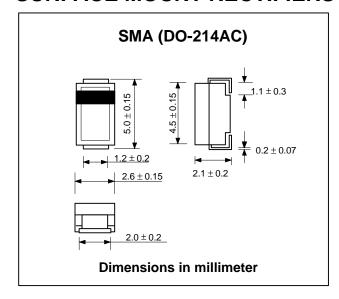
Io: 1.0 Ampere FEATURES

- For surface mounted applications
- Glas@passivated junction
- Low profile package
- Built-in strain relief, ideal for automated placement
- Plastic package has underwrites laboratory flammability Classification 94V-0
- High temperature soldering guaranteed: 250 /10 second at terminals

MECHANICAL DATA

- Case: JEDED SMA (DO-214AC) molded plastic
- Terminals: Plated axial lead solderable per MIL-STD-750, method 2026
- Polarity: Color band denotes cathode end
- Mounting position: Any
- Weight: 0.002ounce, 0.064 gram

SURFACE MOUNT RECTIFIERS



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25 ambient temperature unless otherwise specified.
- Single phase, half wave, 60Hz, resistive or inductive load.
- For capacitive load derate current by 20%

		SYMBOLS	M1	M2	M 3	M4	M5	M6	M7	UNIT
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage		V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current (see Fig.1)		I _{F(AV)}	1.0							A umps
Peak Forward Surge Current 8.3ms single half sine wave superimposed on rated load (JEDEC method) T_L =90		I_{FSM}	30							Amps
Maximum Instantaneous Forward Voltage at 1.0A		V_{F}	1.1							Vαlts
Maximum DC Reverse Current at rated DC Blocking Voltage at	$T_A = 25$	I_R	5.0							μĀ
	$T_A = 125$		50							
Typical Junction Capacitance (NOTE 1)		$R_{\theta JA}$	50							/W
		$R_{ heta JL}$	90							
Typical Thermal Resistance (NOTE 2)		t_{rr}	1.8							μs
Operating and Storage Temperature Range		T_{J},T_{STG}	-55 to +150							

Notes:

- 1. Thermal resistance from Junction to ambient and from junction to lead mounted on $0.2 \times 0.2''$ (5.0 × 5.0mm) copper pad areas.
- 2. Reverse recovery test condition: I_F=0.5A, I_R=1.0A, Irr=0.25A

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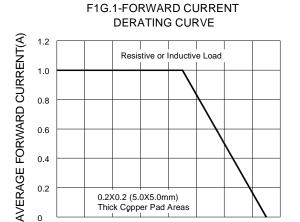






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Thick Copper Pad Areas

60

F1G.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

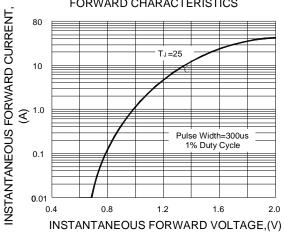
LEAD TEMPERATURE,(

80

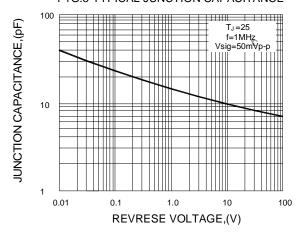
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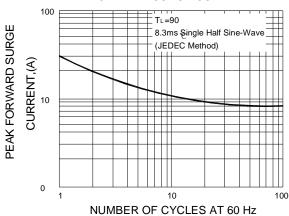
140



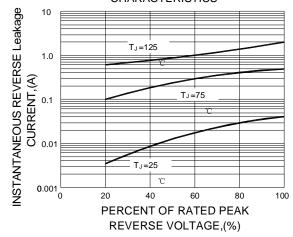
F1G.5-TYPICAL JUNCTION CAPACITANCE



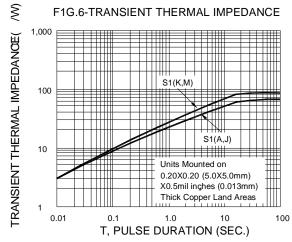
F1G.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



F1G.4-TYPICAL REVERSE **CHARACTERISTICS**



F1G.6-TRANSIENT THERMAL IMPEDANCE



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